



SOD123F Rectifier

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu).	CAS no., if known	Substance mass (mg)	% OF Weight (%)	PPM Of Total Weight
Lead Frame 24.41%	Copper (Cu)	7440-50-8	4.34835	99.9621	244015.2
	Phosphorus (P)	7723-14-0	0.00007	0.0016	3.9
	Arsenic (As)	7440-38-2	0.00008	0.0018	4.5
	Tin (Sn)	7440-31-5	0.00008	0.0018	4.5
	Oxygen (O)	7782-44-7	0.00004	0.0009	2.2
	Sulfur (S)	7704-34-9	0.00095	0.0218	53.3
	Iron (Fe)	7439-89-6	0.00005	0.0011	2.8
	Nickel (Ni)	7440-02-0	0.00002	0.0005	1.1
	Bismuth (Bi)	7440-69-9	0.00015	0.0034	8.4
	Antimony (Sb)	1309-64-4	0.00016	0.0037	9.0
	Lead (Pb)	7439-92-1	0.00003	0.0007	1.7
	Zinc (Zn)	7440-66-6	0.00002	0.0005	1.1
	Total		4.35		
Solder Wafer 6.18%	Lead (Pb)	7439-92-1	1.0175	92.50	57,098.8
	Tin (Sn)	7440-31-5	0.0550	5.00	3086.4
	Silver (Ag)	7440-22-4	0.0275	2.50	1543.2
	Total		1.10		
Chip 3.37%	Silicon (Si)	7440-21-3	0.572	95.40	32,121.2
	Lead (Pb)	7439-92-1	0.028	4.60	1,548.8
	Total		0.60		
Molding 58.67%	Silica (SiO ₂)	14808-60-7	7.744	74.11	434,595.7
	Epoxy resin	29690-82-2	1.777	17.00	99,691.4
	Phenolic resin	9003-35-4	0.920	8.80	51,604.9
	Phosphorus(P)	7723-14-0	0.005	0.05	293.2
	Carbon Black	1333-86-4	0.004	0.04	234.6
	Total		10.45		
Plating 7.37%	Tin (Sn)	7440-31-5	1.323	100.00	74,242.4
	Total		1.32		
	Total mass (mg)		17.82		